

Two part thermal gel pad XK-S25

Features:

- 1:1 mix
- (no cure by-product)
- Low stress applications
- Easy to use
- Fast cure by heating



Applications

- Automotive electronics
- Telecommunications
- Computer&peripherals
- Thermally conductive & vibration dampening
- Between any heat-generating semiconductor and a heat sink

	XK-S25	METHOD	UNIT
Color / Part A	Pink	Visual	
Color / Part B	White	Visual	
Features	Soft GEL	-	-
Density	2.9	ASTM D792	g/cm3

Before Cured Property

A:B	1:1	-	-
Mixed Viscosity (20rpm)	Paste	ASTM D2196	Cps
Shelf Life @ 25°C	6 month		

After Cured Property

Color	yellow	Visual	-
Cure Schedule 1	10hr/25°C		
Cure Schedule 2	60min/80 °C		
Cure Schedule 3	10min/100°C		
Working time	60 min/25°C		
Hardness	Shore 00 = 50	ASTM D2240	
	AskerC = 25	JIS K7312	
Tensile Strength.	0.2	ASTM D412	Mpa
Elongation	50	ASTM D412	%
Continuous Use Temp	-60~200		°C

Electrical Property

Dielectric strength	>10	ASTM D149	KV/mm
Volume resistivity	>10 ¹³	ASTM D257	Ohm-cm
Dielectric Constant	8	ASTM D150	(1KHz)
Flame Rating	V-0	UL94	

Thermal Property

Thermal Conductivity	2.5	ASTM D5470	W/m*K
Heat Capacity	1	ASTM E1269	J/g-K